



SWTEST
2021 CONFERENCE
PROBE TODAY,
FOR TOMORROW

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ANNIVERSARY

Solutions to New Challenges in Advanced Vertical Guide Plates



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Summary

Introduction

Motivation : A need in the market for higher current Probe Cards

A Simple Mechanical Model

Manufacturing Challenges

Results of 1st Trial

Results of 2nd Trial

Discussion

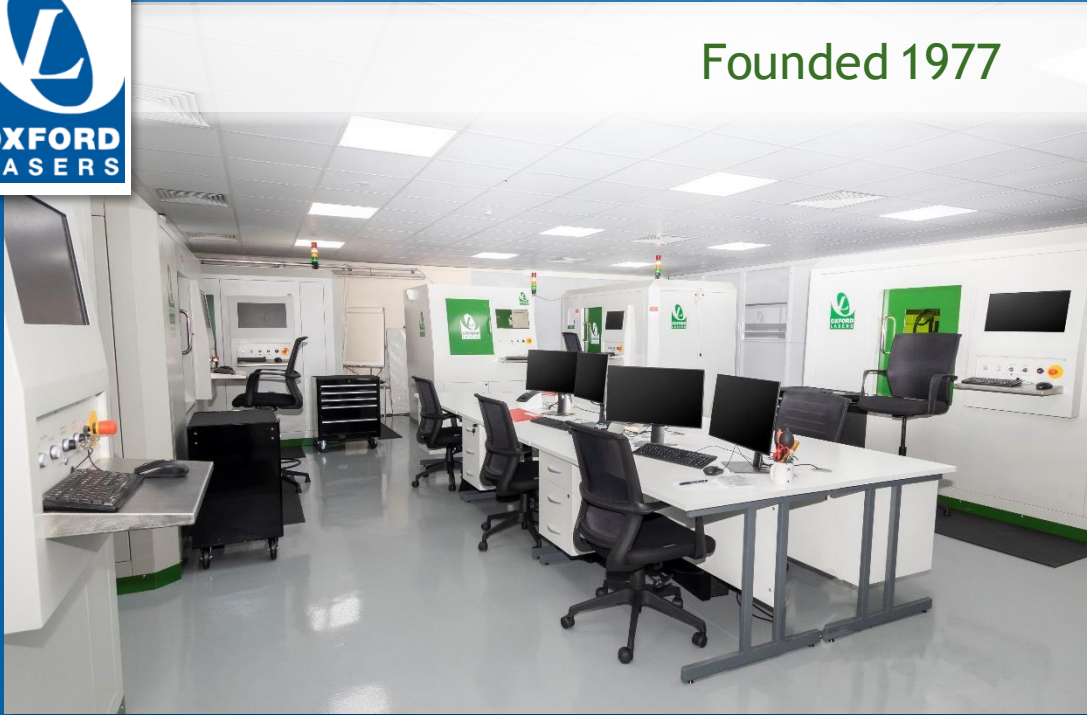
Follow-on Work

Conclusion

Introduction



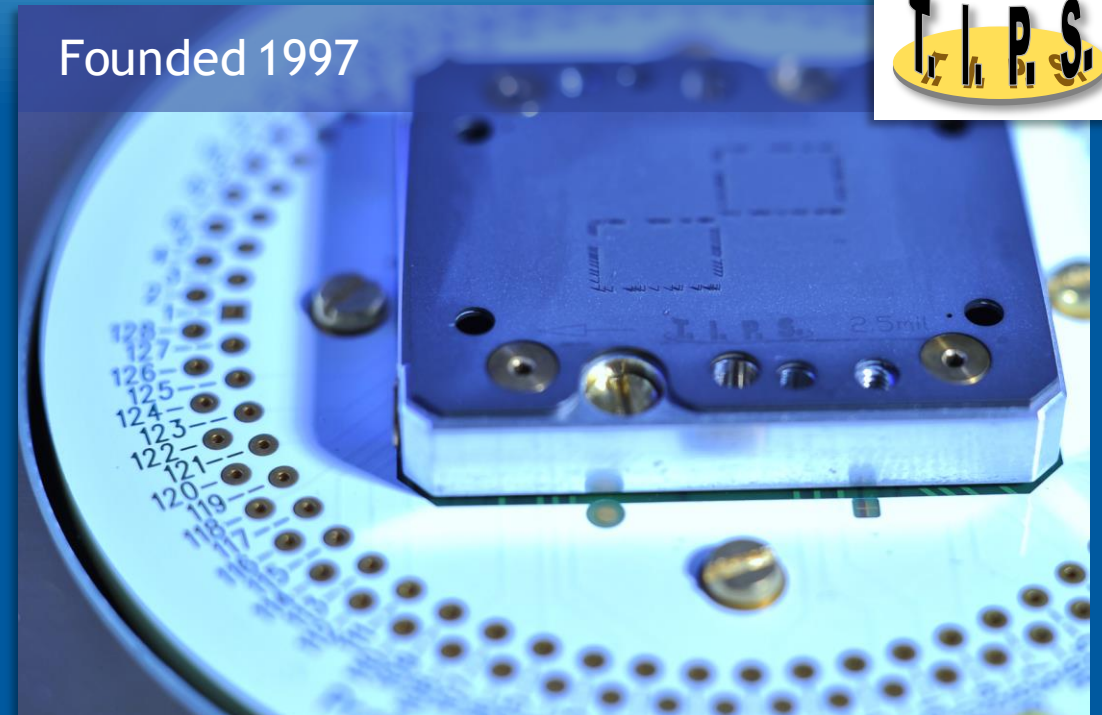
Founded 1977



Specializing in the manufacture of guide plates:

- Over 20 years experience in guide plate production
- World Class subcontract micromachining facility
- Manufacturer of production laser tools

Founded 1997



Specializing in the design and manufacture of test interfaces for semiconductor test:

- High Power Applications
- Probe Cards for Sensor Devices
- Automotive RADAR

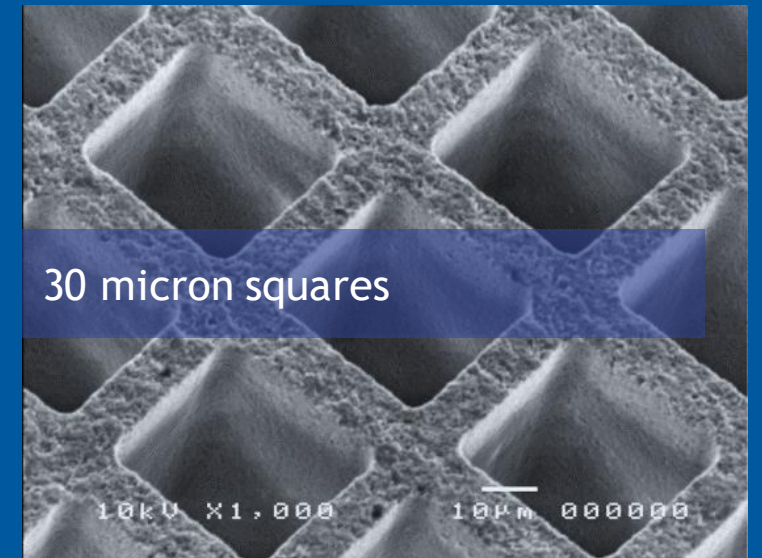
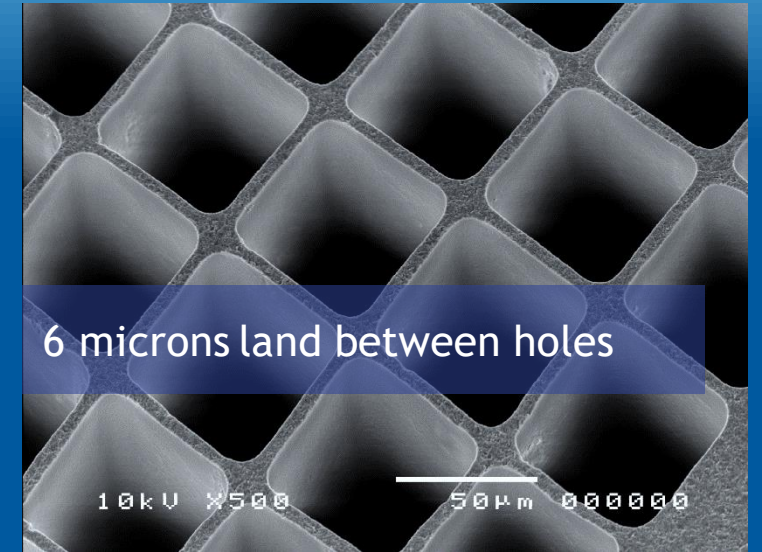
Introduction

Trends in Vertical Probe Cards :

- 1) Smaller Holes
- 2) Tighter Pitch

The focus of this presentation is on tighter pitch :

- two years ago, we focused on achieving tighter pitch
- here, with T.I.P.S, we will show a practical example



Motivation

T.I.P.S have noted an increasing requirement for high current probe cards :

- Requests for 3000A and more
- Vertical probe cards allow much higher current densities compared to cantilever probe cards
- High pin count and high needle density required:
 - Reducing needle pitch to increase overall current
 - Mechanical stress in ceramic guide plates could be a limiting factor

Investigation of **minimum feasible hole pitch** in ceramic guide plates

Our Approach

Development of a basic mechanical model to obtain statements about the mechanical stresses in the ceramic guide plates

Conduct an experimental investigation - considering the findings from the mechanical model

- Discuss feasible wall thickness (Oxford Lasers and T.I.P.S.)
- Experimental setup with specified hole patterns (Provided by T.I.P.S.)
- Manufacturing of the ceramic guide plates (Oxford Lasers)
- Durability testing of the assembled vertical probe head (Conducted at T.I.P.S.)

Revisit the mechanical model with outcome from experimental investigations

Goal:

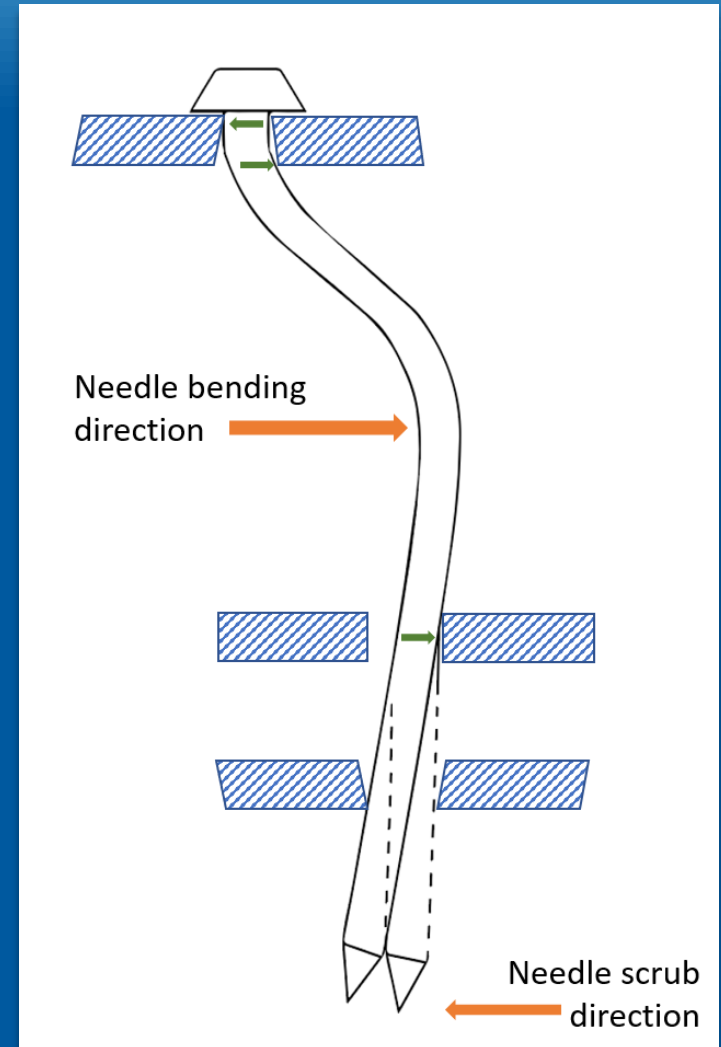
- **Establish guidelines for designing needle arrangements for given current and pad size / shapes**

A Simple Mechanical Model

Mechanical model – Needle forces

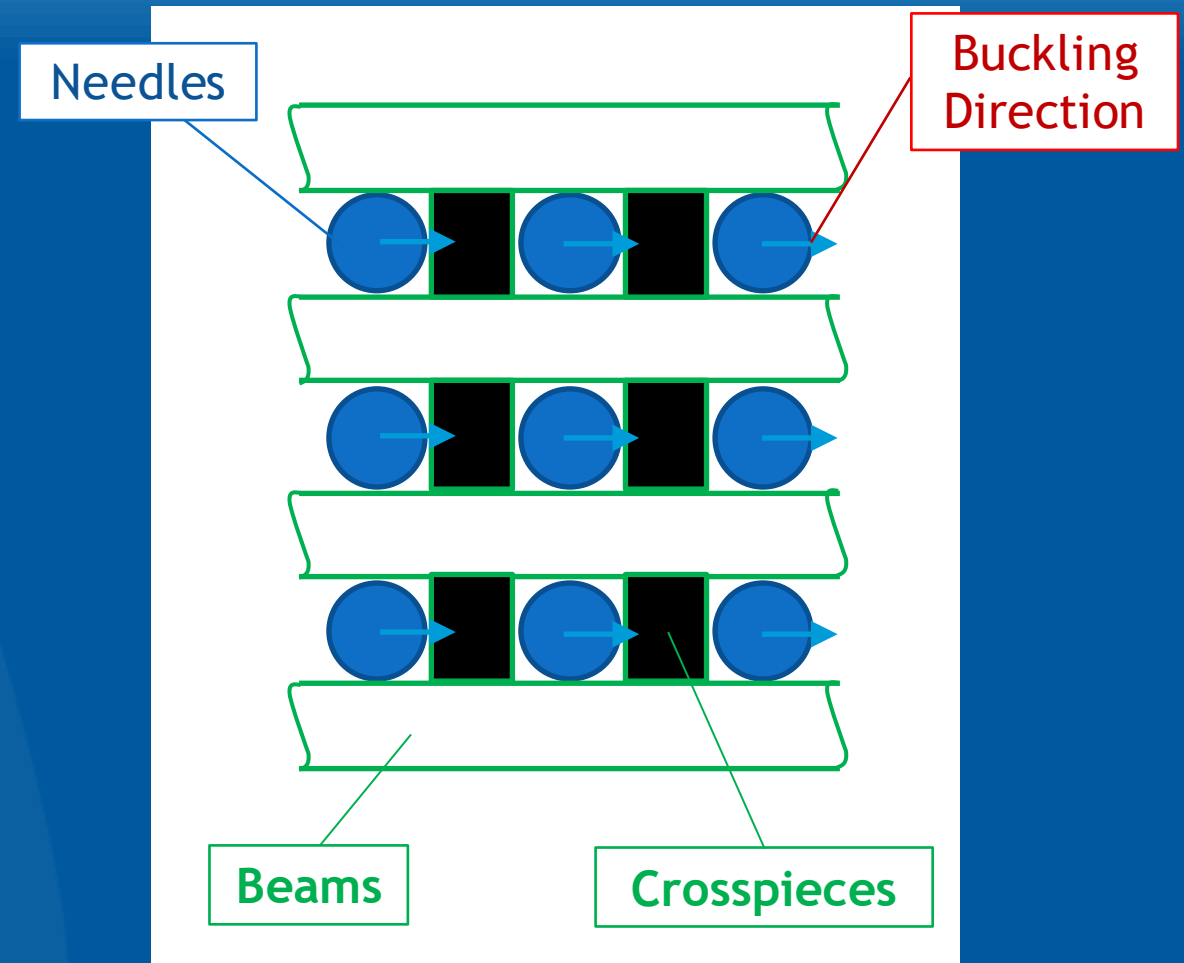
Bending forces can be calculated from bending line of needle, dependent on:

- Needle diameter and length
- Distance between ceramic plates
- Overtravel
- Young's modulus of needle material



A Simple Model

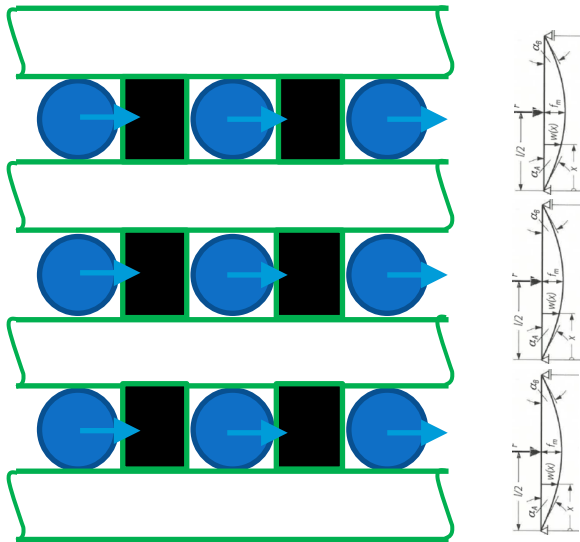
- Simple hole pattern in ceramic plate
- Material between holes to be considered cuboidal
- Buckling direction parallel to beam alignment



A Simple Model

Crosspiece

Calculated as “beam in bending”



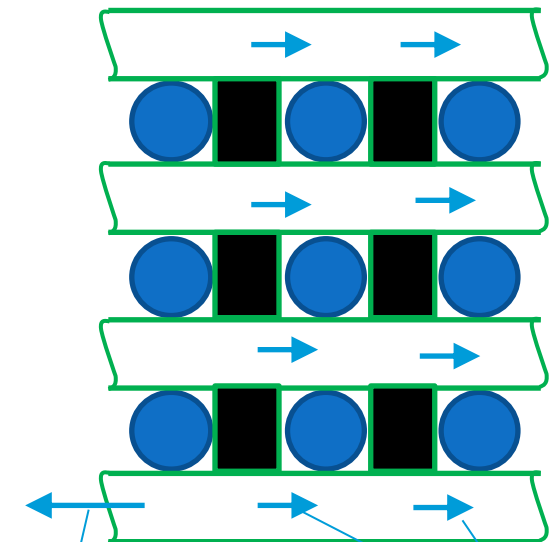
C 22 Festigkeitslehre – 2 Beanspruchung stabförmiger Bauteile

Tabelle 5a. Biegelinien von statisch bestimmten Trägern mit konstantem Querschnitt

Belastungsfall	Gleichung der Biegelinie
	$0 \leq x \leq l/2:$ $w(x) = \frac{Fl^3}{48EI_y} \left[3\frac{x}{l} - 4\left(\frac{x}{l}\right)^3 \right]$

Beam

Stressed by tensile force of crosspiece



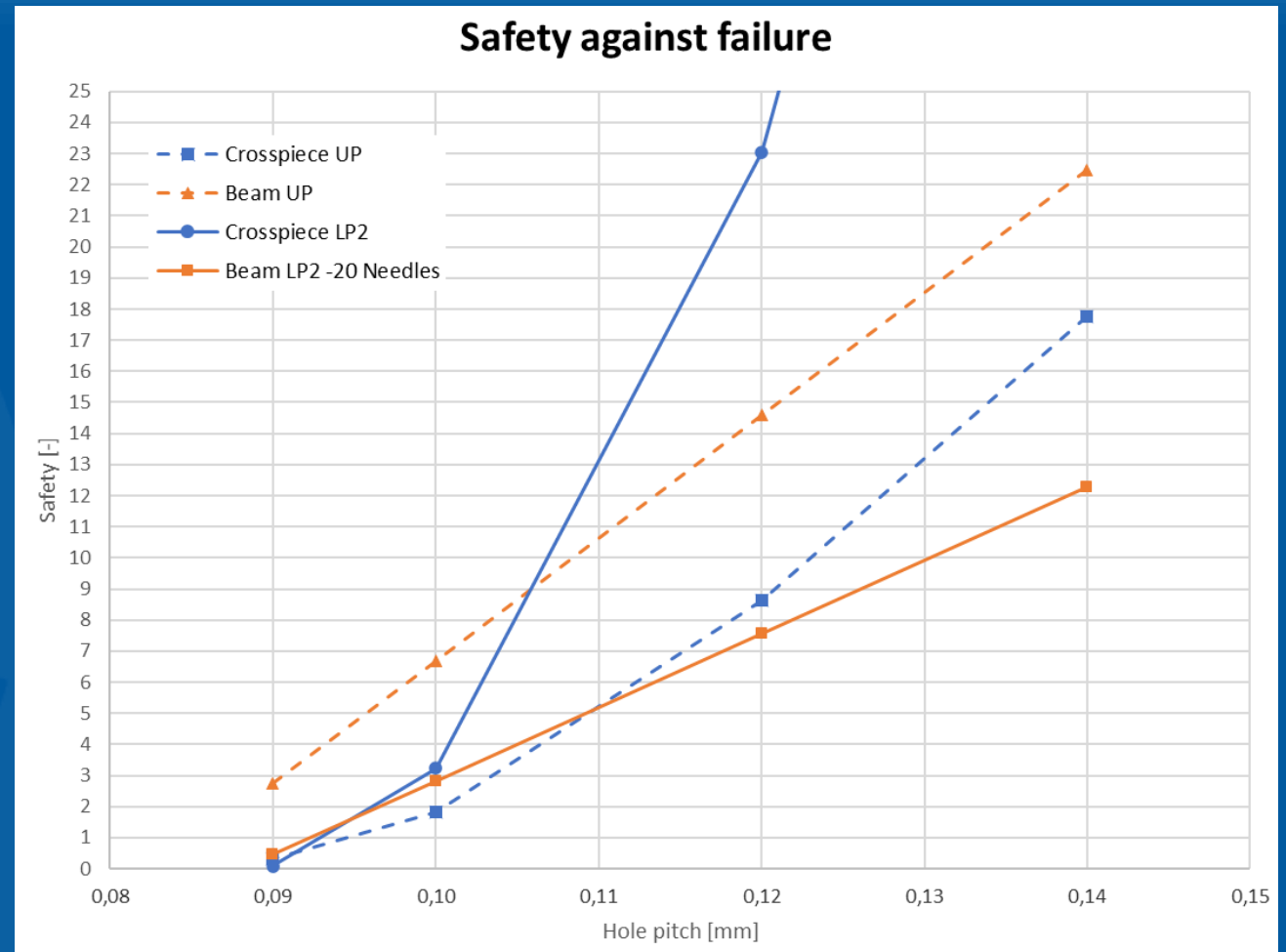
Accumulated tensile force

$$\sigma_{max} = \frac{F \cdot n_{needle}}{A_{beam}}$$

Simple Mechanical Model - Findings

- Simplified model provides basic correlation, but has too many uncertainties
- Absolute values are not that reliable, but
 - **Upper plate:**
 - Crosspiece seems more critical
 - **Lower plate:**
 - Depending on number of needles in buckling direction, beam seems more critical

Experimental investigations needed

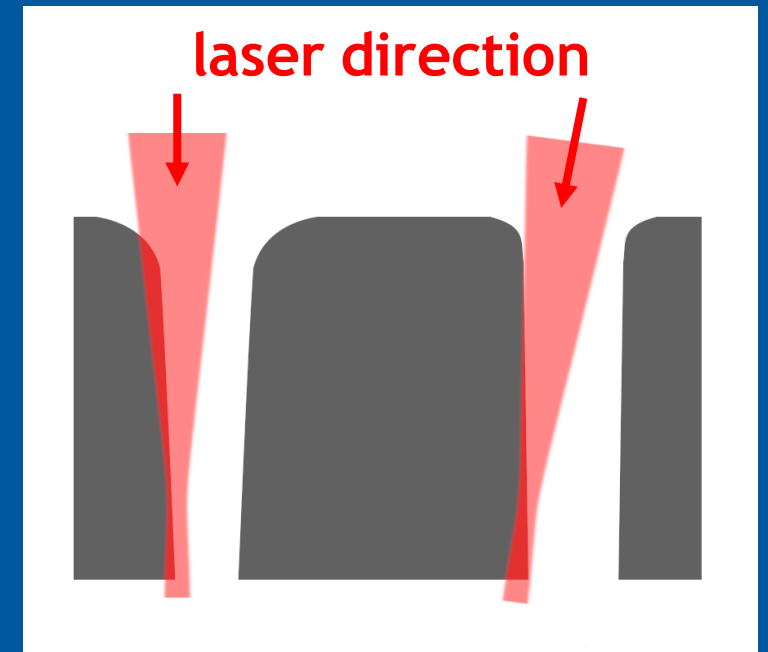


Manufacturing Challenges

Drilling holes on tighter and tighter pitch

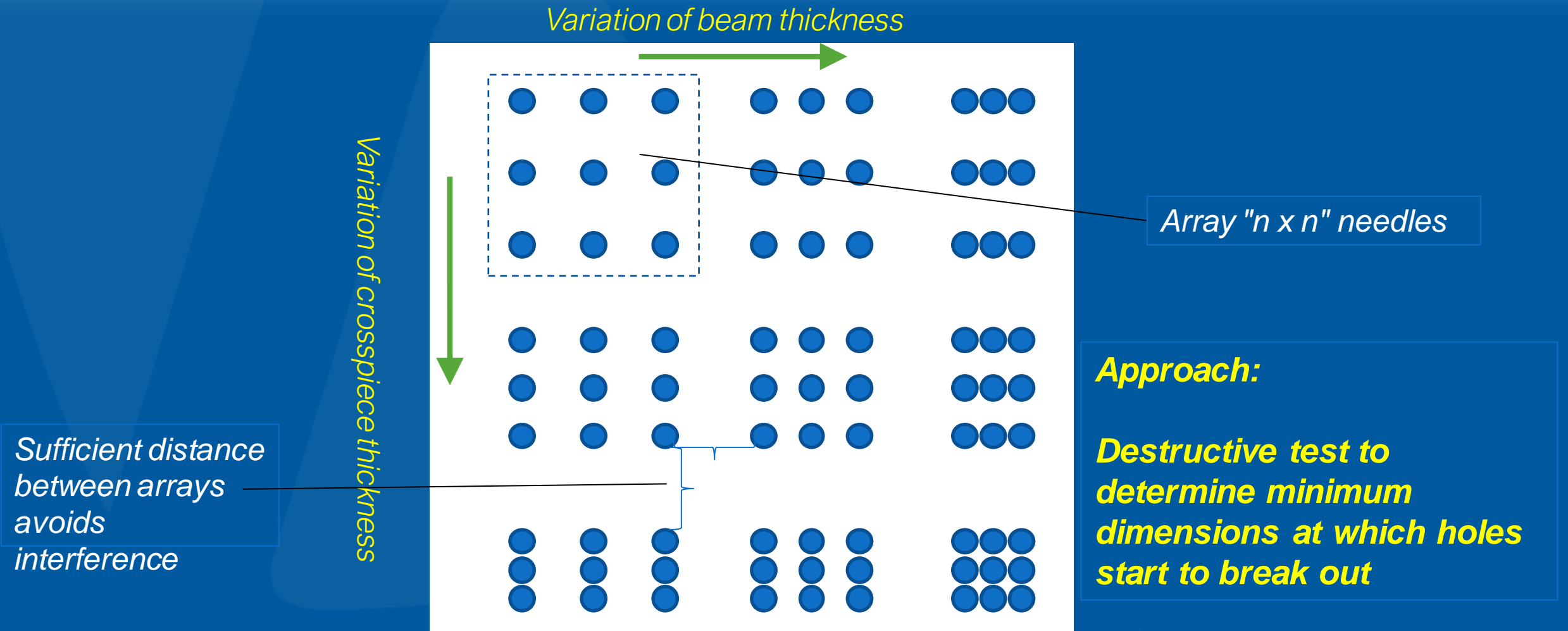
Some factors to be considered :

- Variety of hole diameters in different plates making up each probe head
- Deliberate taper requirements to assist needle movement
- Entry rounding on the laser entry side of the drilled hole
- Structural integrity of wall

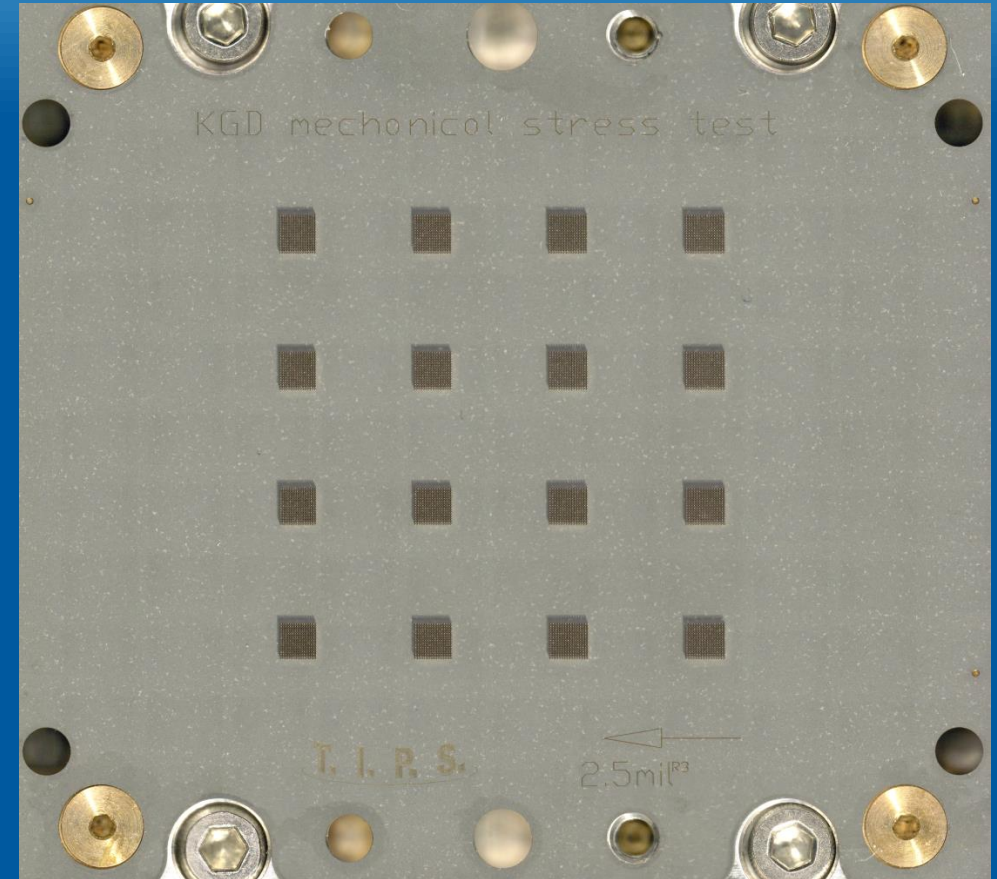
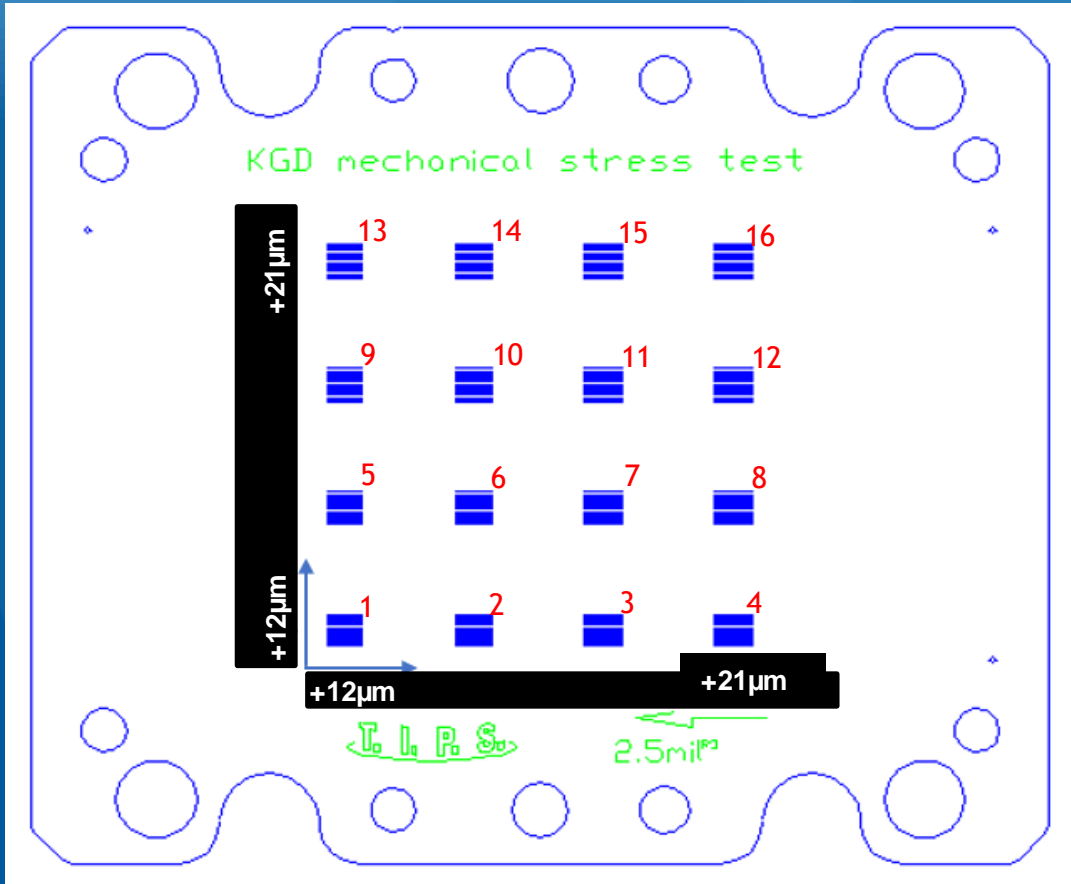


Experimental Work – First Trial

Variation of hole pitch in both directions to find out critical wall thickness



First Trial



Test Conditions :

Overtravel : Maximum Overtravel
Touchdowns : > 20,000

Test Method :

Disassemble probe head
Check for ceramic plate failure
Repeat

Results from First Trial

Pleasingly all arrays passed :

- no broken ceramics
- nothing exciting to show

Shows that model is just an indicator

Next step - To reduce the hole pitch further

Test plates with hole to hole wall thickness of 10 microns and 8 microns

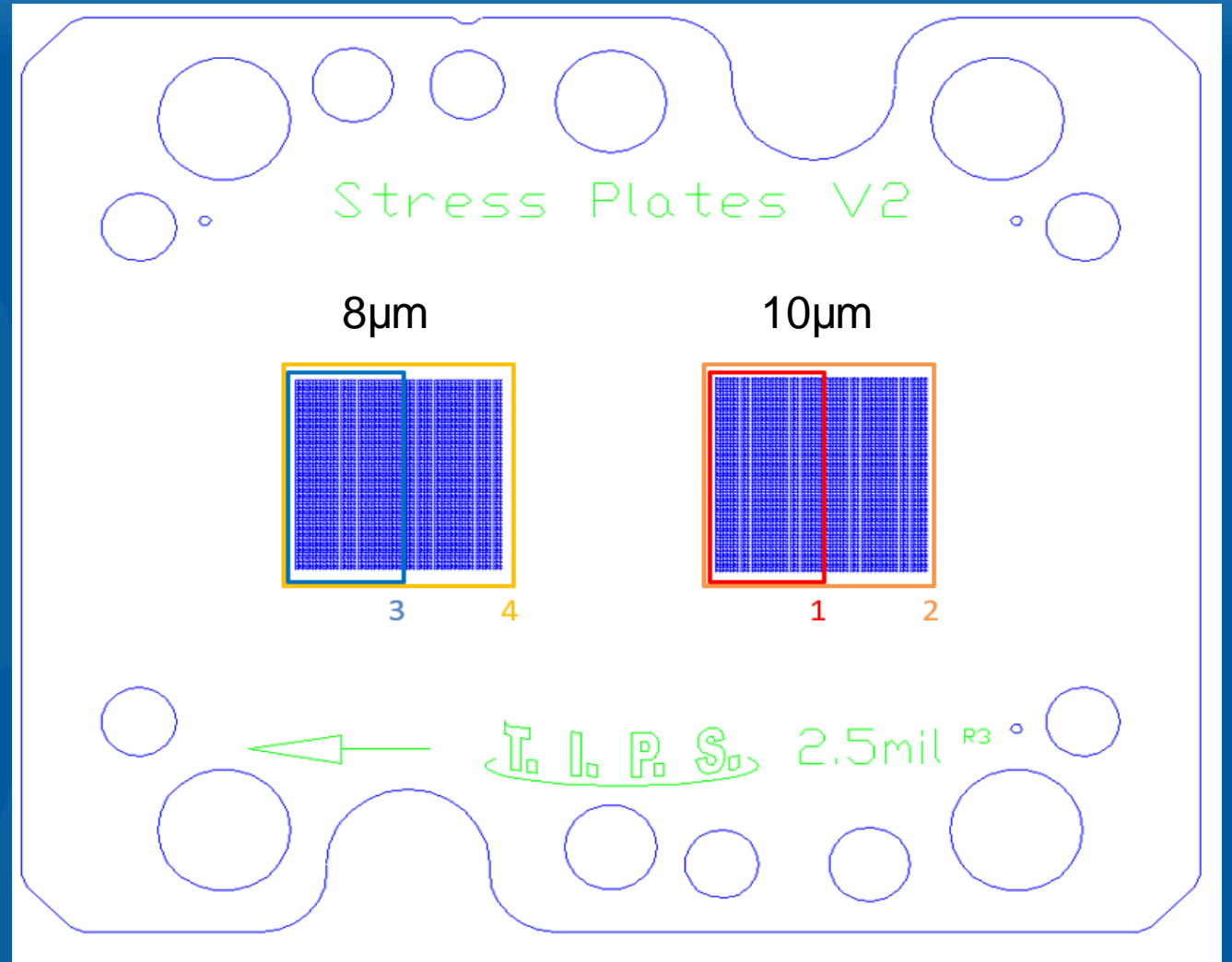
Second Trial

Two further test conditions :

- Minimum wall thickness 10 microns
 - Array 1
 - Array 2
- Minimum wall thickness 8 microns
 - Array 3
 - Array 4

Testing Protocol :

Maximum overtravel
50,000 touchdowns
Disassemble probe head
Check for ceramic plate failure
Repeat



Second Trial Results

Results from the two further test conditions :

- Minimum wall thickness 10 microns
 - Array 1 ✓
 - Array 2 ✓
- Minimum wall thickness 8 microns
 - Array 3 ✗

Testing Protocol :

Maximum overtravel

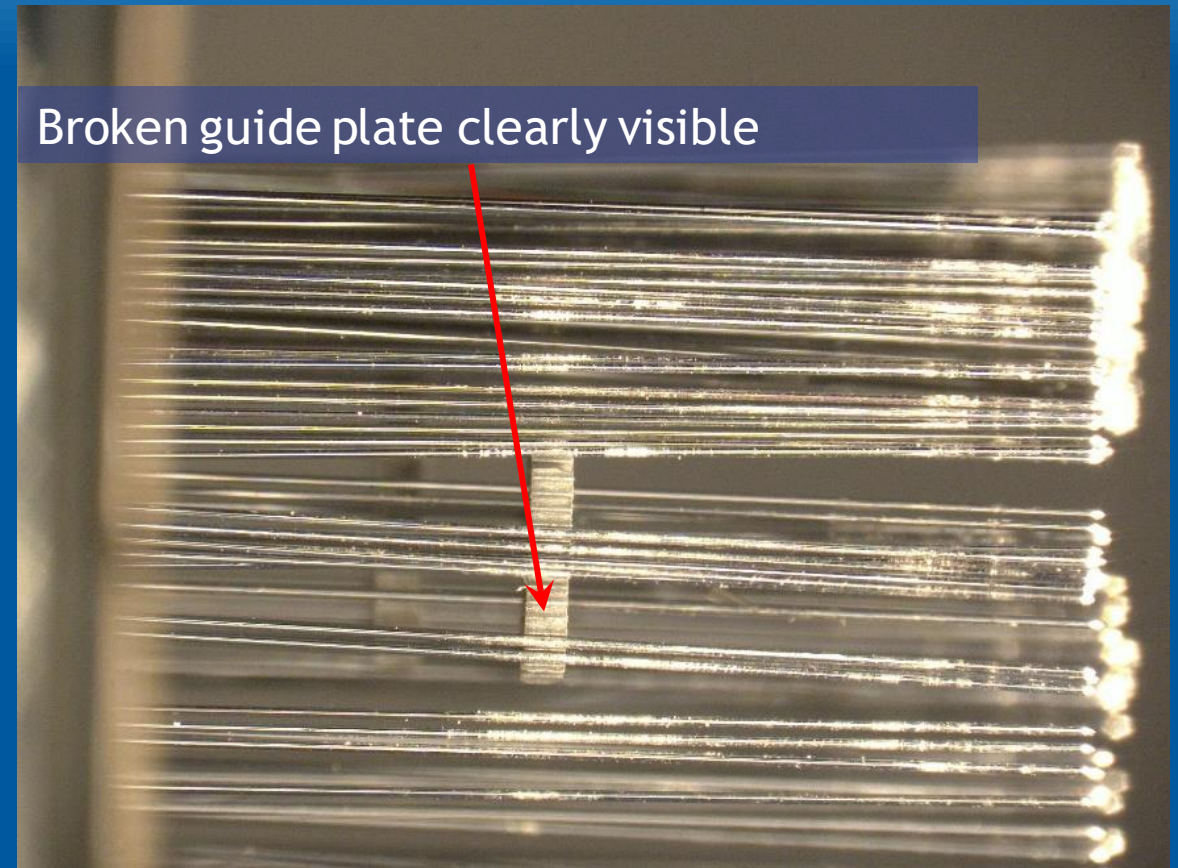
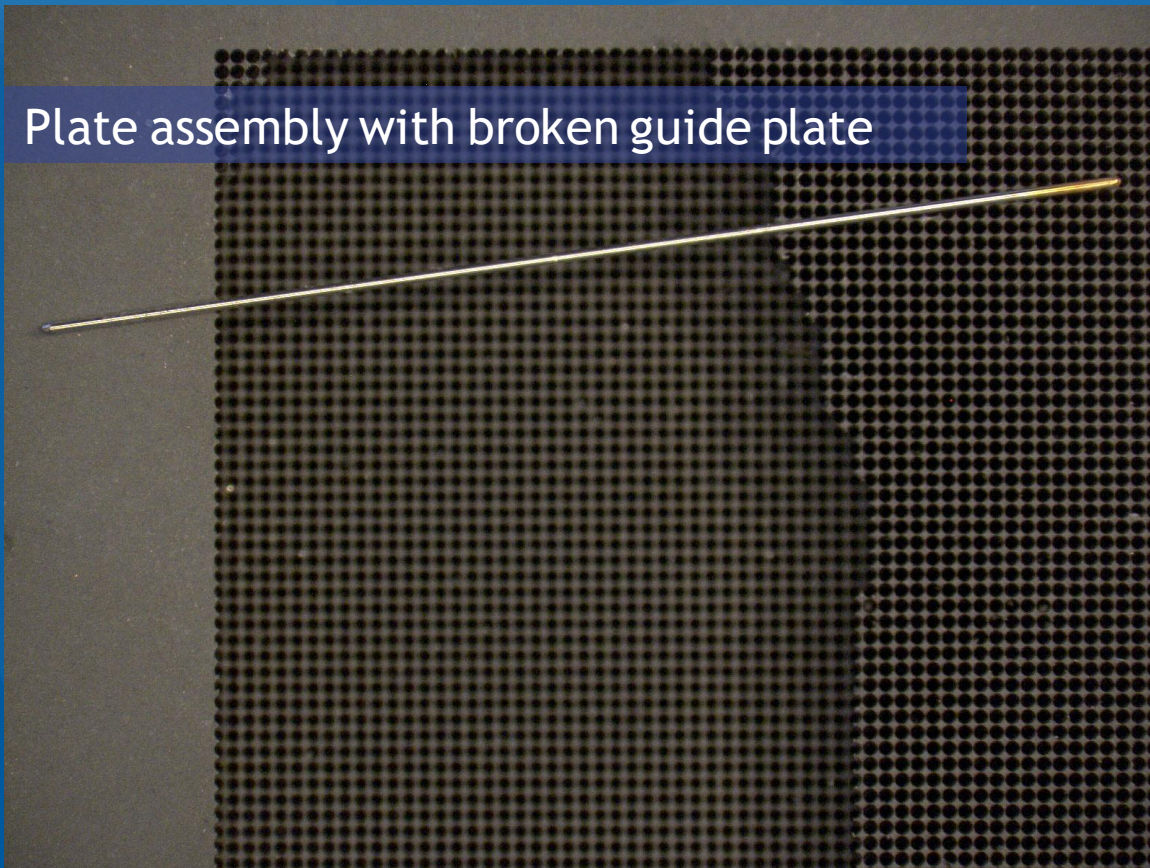
50,000 touchdowns

Disassemble probe head

Check for ceramic plate failure

Repeat

Results from Second Trial



Discussion

- Simple mechanical model gives good understanding of forces involved
 - Not accurate enough to do predictions
 - Calculations err “on the side of safety”
- Experimental verification gave good insights into actual mechanical stress limits
- Raises questions on the limits of tight pitch in certain circumstances
- Expect to be different for different plate thicknesses and materials

Follow-on Work

- Improve the Mechanical Model
- Check repeatability of this work under a variety of conditions
- Investigate other materials

Conclusion

- Simple model gives some indication, but needs further refinement / experimental investigation - much more complex - but good to get understanding of forces
- Demonstrated an improvement on pitch reduction performance of 26% in both directions
 - Increase of current density of almost 60% on same chip size!
- Possible to design a Probe Card that is both :
 - manufacturable and
 - has a safety margin built in
- Satisfies the customers high current requirements

Thanks

My thanks for this work go to :

From T.I.P.S :

Dr Rainer Gaggl
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Meinhart Jeschke

From Oxford Lasers :

Michael Gaukgroger
Mark Cheverton

Thank you for your Attention